

## Features

- Low Leakage
- Low Clamping Voltage
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

## ESD Protection Device

## Maximum Ratings

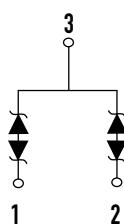
IEC61000-4-2 (ESD)	Air	$\pm 30\text{KV}$
	Contact	$\pm 30\text{KV}$
Peak Pulse Power (8/20 $\mu\text{s}$ ) <sup>(Note 2)</sup>	$P_{PK}$	250W
Operating Junction Temperature Range	$T_J$	-55°C to +150°C
Storage Temperature Range	$T_{STG}$	-55°C to +150°C

Note :

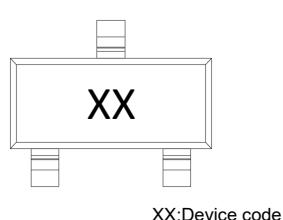
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

2. Non-repetitive current pulse 8/20  $\mu\text{s}$  exponential decay waveform according to IEC61000-4-5.

### Internal Structure

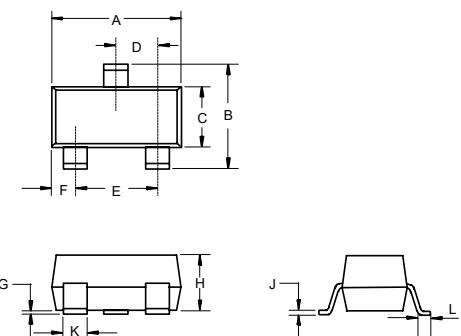


### Marking Code



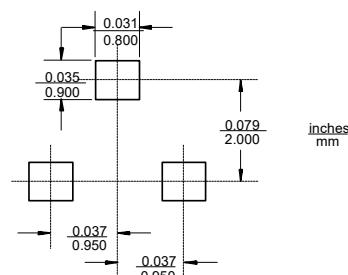
MCC Part No.	Device Code
ESD3V3T2B	3B.
ESD7V0T2B	7B.
ESD12VT2B	12B.
ESD15VT2B	15B.
ESD24VT2B	6RS.
ESD27VT2B	27B.
ESD36VT2B	36B.

### SOT-23

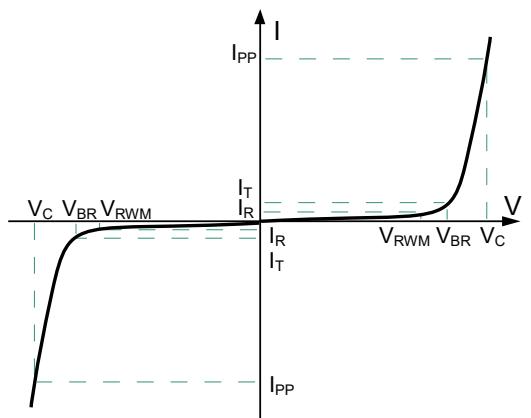


DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.110	0.120	2.80	3.04	
B	0.083	0.104	2.10	2.64	
C	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
E	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
H	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

### Suggested Solder Pad Layout



Symbol	Parameter
$V_{RWM}$	Peak Reverse Working Voltage
$I_R$	Reverse Leakage Current @ VRWM
$V_{BR}$	Breakdown Voltage @ IT
IT	Test Current
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ IPP
$P_{PK}$	Peak Pulse Power
$C_J$	Junction Capacitance



### Electrical Characteristics @ 25°C (Unless Otherwise Specified)

#### ESD3V3T2B

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Working Voltage	$V_{RWM}$				3.3	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1\text{mA}$	5			V
Reverse Leakage Current	$I_R$	$V_{RWM}=3.3\text{V}$			0.5	$\mu\text{A}$
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=1\text{A}, t_p=8/20\mu\text{s}$			9	V
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=25\text{A}, t_p=8/20\mu\text{s}$			16	V
Junction Capacitance	$C_J$	$V_R=0\text{V}, f=1\text{MHz}$		100		pF
Dynamic Resistance <sup>Note2</sup>	$R_{DYN}$	TLP, $t_p=100\text{ns}$		0.18		$\Omega$

#### ESD7V0T2B

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Working Voltage	$V_{RWM}$				7	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1\text{mA}$	7			V
Reverse Leakage Current	$I_R$	$V_{RWM}=7\text{V}$			0.5	$\mu\text{A}$
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=1\text{A}, t_p=8/20\mu\text{s}$			13	V
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=17\text{A}, t_p=8/20\mu\text{s}$			15	V
Junction Capacitance	$C_J$	$V_R=0\text{V}, f=1\text{MHz}$		65		pF
Dynamic Resistance <sup>Note2</sup>	$R_{DYN}$	TLP, $t_p=100\text{ns}$		0.37		$\Omega$

### ESD12VT2B

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Working Voltage	$V_{RWM}$				12	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1mA$	13			V
Reverse Leakage Current	$I_R$	$V_{RWM}=12V$			0.5	$\mu A$
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s$			20	V
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=10A, t_p=8/20\mu s$			30	V
Junction Capacitance	$C_J$	$V_R=0V, f=1MHz$		35		pF
Dynamic Resistance <sup>Note2</sup>	$R_{DYN}$	TLP, $t_p=100ns$		0.28		$\Omega$

### ESD15VT2B

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Working Voltage	$V_{RWM}$				15	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1mA$	16			V
Reverse Leakage Current	$I_R$	$V_{RWM}=15V$			0.5	$\mu A$
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s$			20	V
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=9A, t_p=8/20\mu s$			30	V
Junction Capacitance	$C_J$	$V_R=0V, f=1MHz$		30		pF
Dynamic Resistance <sup>Note2</sup>	$R_{DYN}$	TLP, $t_p=100ns$		0.4		$\Omega$

### ESD24VT2B

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Working Voltage	$V_{RWM}$				24	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1mA$	26			V
Reverse Leakage Current	$I_R$	$V_{RWM}=24V$			0.5	$\mu A$
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s$			34	V
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=7A, t_p=8/20\mu s$			44	V
Junction Capacitance	$C_J$	$V_R=0V, f=1MHz$		20		pF
Dynamic Resistance <sup>Note2</sup>	$R_{DYN}$	TLP, $t_p=100ns$		0.83		$\Omega$

### ESD27VT2B

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Working Voltage	$V_{RWM}$				27	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1\text{mA}$	31			V
Reverse Leakage Current	$I_R$	$V_{RWM}=27\text{V}$			0.5	$\mu\text{A}$
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=1\text{A}, t_p=8/20\mu\text{s}$			50	V
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=6\text{A}, t_p=8/20\mu\text{s}$			70	V
Junction Capacitance	$C_J$	$V_R=0\text{V}, f=1\text{MHz}$		15		pF
Dynamic Resistance <sup>Note2</sup>	$R_{DYN}$	TLP, $t_p=100\text{ns}$		1.1		$\Omega$

### ESD36VT2B

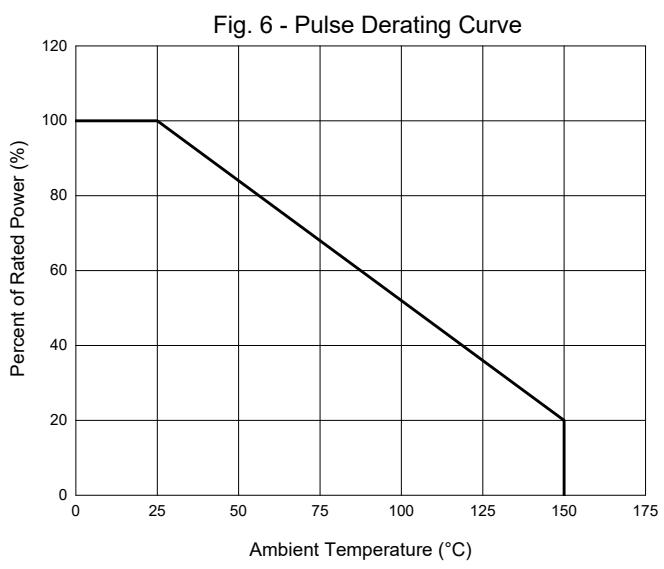
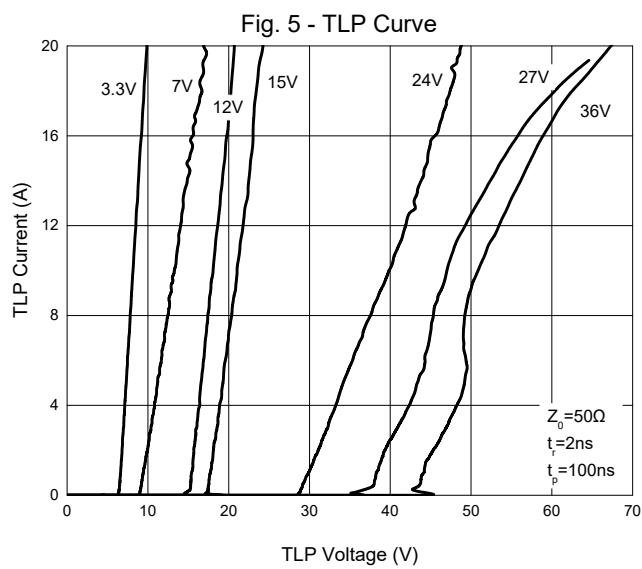
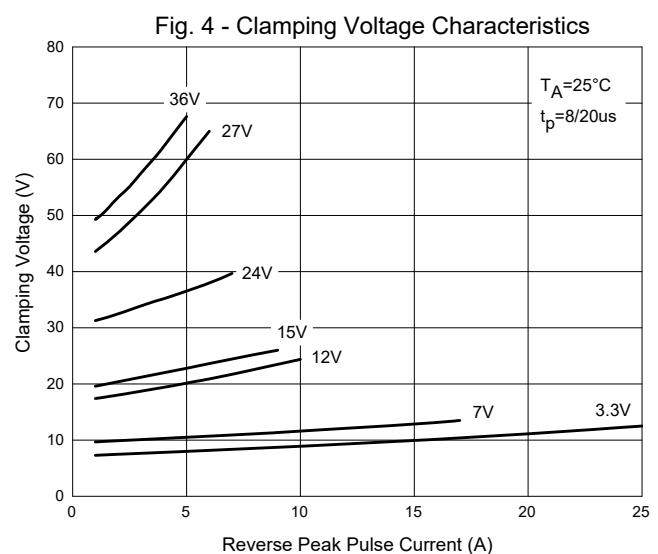
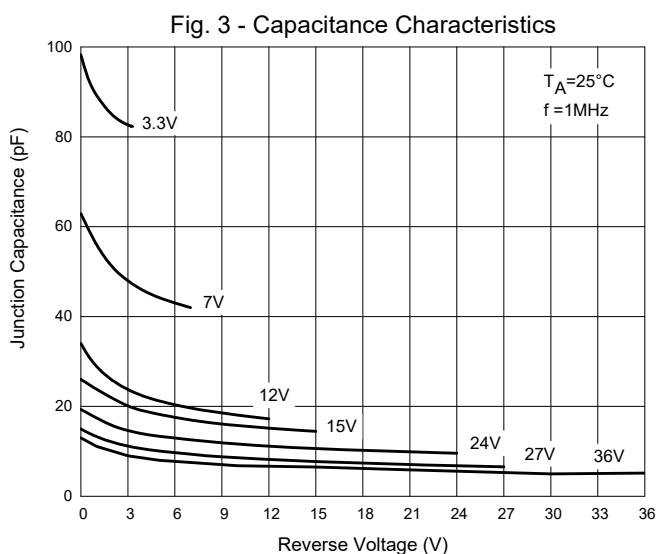
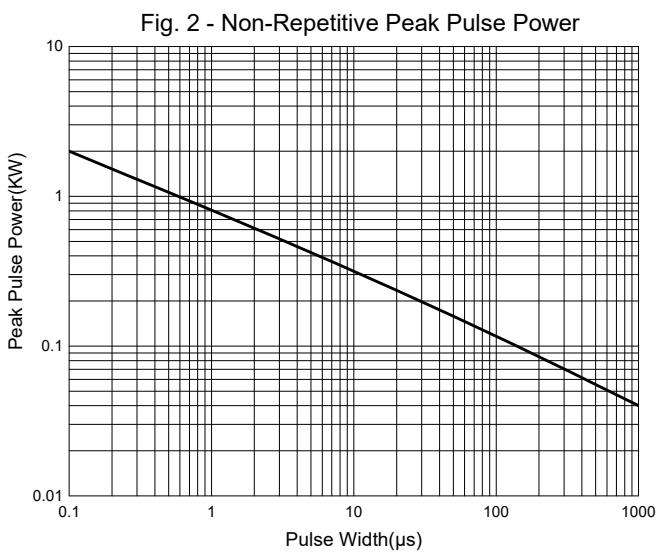
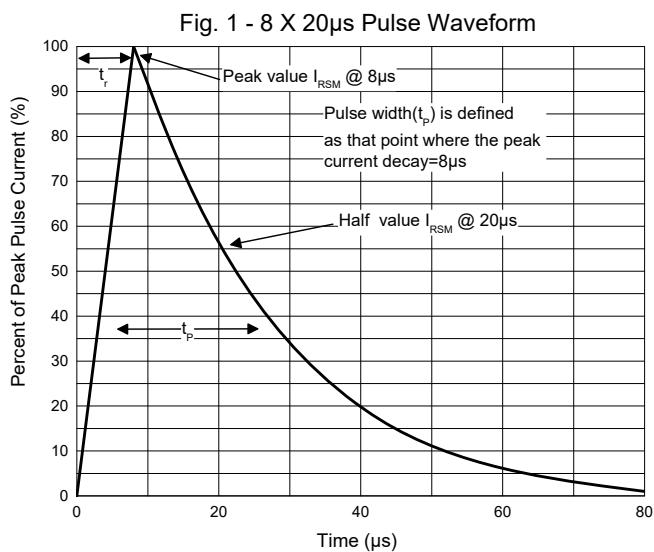
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Working Voltage	$V_{RWM}$				36	V
Reverse Breakdown Voltage	$V_{BR}$	$I_T=1\text{mA}$	38			V
Reverse Leakage Current	$I_R$	$V_{RWM}=36\text{V}$			0.5	$\mu\text{A}$
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=1\text{A}, t_p=8/20\mu\text{s}$			55	V
Clamping Voltage <sup>Note1</sup>	$V_C$	$I_{PP}=5\text{A}, t_p=8/20\mu\text{s}$			90	V
Junction Capacitance	$C_J$	$V_R=0\text{V}, f=1\text{MHz}$		13		pF
Dynamic Resistance <sup>Note2</sup>	$R_{DYN}$	TLP, $t_p=100\text{ns}$		0.9		$\Omega$

Note :

1. Non-repetitive current pulse 8/20 $\mu\text{s}$  exponential decay waveform according to IEC61000-4-5.

2. TLP parameter:  $Z_0=50\Omega$ ,  $t_p=100\text{ns}$ ,  $t_r=2\text{ns}$ , averaging window from 60ns to 80ns. RDYN is calculated from 4A to 16A.

## Curve Characteristics



## Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 3Kpcs/Reel

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